

11-04-2009



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To the Director of the U.S. Patent

103579573

documents or the new address(es) below.

1. Name of conveying party(ies):

Toshinori Kanemoto (04/14/2009) and Tadashi Morita (04/15/2009)

Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies)

Name: Sony Corporation

Internal Address: \_\_\_\_\_

Street Address: \_\_\_\_\_

1-7-1 Konan  
Minato-Ku, Tokyo  
108-0075  
JAPAN

City: \_\_\_\_\_

State: \_\_\_\_\_

Country: \_\_\_\_\_ Zip: \_\_\_\_\_

Additional name(s) & address(es) attached?  Yes  No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): in parentheses after inventor name

Assignment  Merger  Change of Name

Security Agreement  Joint Research Agreement

Government Interest Assignment

Executive Order 9424, Confirmatory License

Other \_\_\_\_\_

4. Application or patent number(s):

This document is being filed together with a new application.

A. Patent Application No.(s)

12/309,475

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Christopher M. Tobin  
RADER, FISHMAN & GRAUER PLLC

Internal Address: Atty. Dkt.: SON-3797  
Street Address: 1233 20th Street, N.W.  
Suite 501

City: Washington

State: DC Zip: 20036

Phone Number: (202) 955-3750

Fax Number: (202) 955-3751

Email Address: cmt@raderfishman.com

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

Authorized to be charged to deposit account

Enclosed

None required (government interest not affecting title)

8. Payment Information

Deposit Account Number 18-0013

Authorized User Name Christopher M. Tobin

9. Signature:

Signature

October 30, 2009

Date

Christopher M. Tobin - 40,290

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

3

10-30-09

## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

**ELECTRONIC APPARATUS, INFORMATION PROCESSING METHOD,  
AND PROGRAM**

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, **Sony Corporation**, located and doing business at **1-7-1 Konan, Minato-ku, Tokyo, 108-0075 JAPAN**, (hereinafter referenced as ASSIGNEE) are desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 12/309,475, Filing Date: January 21, 2009.

This assignment executed on the dates indicated below.

Toshinori Kanemoto

Name of first inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of first inventor

Toshinori Kanemoto

Signature of first inventor

April 14, 2009

Date of this assignment

Tadashi Morita

Name of second inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

Tadashi Morita

Signature of second inventor

April 15, 2009

Date of this assignment